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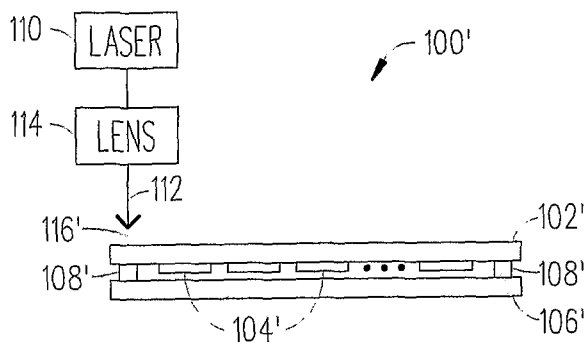
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(54) Title: HERMETICALLY SEALED GLASS PACKAGE AND METHOD OF FABRICATION



(57) Abstract: A hermetically sealed glass package and method
for manufacturing the hermetically sealed glass package are de-
scribed herein using an OLED display as an example. In one em-
bodiment, the hermetically sealed glass package is manufactured
by providing a first substrate plate and a second substrate plate.
The second substrate contains at least one transition metal such
as iron, copper, vanadium, manganese, cobalt, nickel, chromium,
and/or neodymium. A sensitive thin-film device that needs protec-
tion is deposited onto the first substrate plate. A laser is then used
to heat the doped second substrate plate in a manner that causes
a portion of it to swell and form a hermetic seal that connects the
first substrate plate to the second substrate plate and also protects
the thin film device. The second substrate plate is doped with at

least one transition metal such that when the laser interacts with it there is an absorption of light from the laser in the second substrate
plate, which leads to the formation of the hermetic seal while avoiding thermal damage to the thin-film device. Another embodiment
of the hermetically sealed glass package and a method for manufacturing that hermetically sealed glass package are also described
herein.

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